

WIDEBAND GENERAL PURPOSE AMPLIFIER

Typical Applications

- General Purpose High Bandwidth Gain **Blocks**
- IF or RF Buffer Amplifiers

- Broadband Test Equipment
- Final PA for Medium Power Applications
- Driver Stage for Power Amplifiers

Product Description

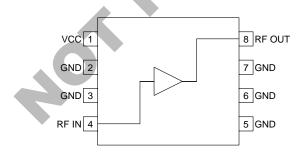
The RF2310 is a general purpose, low-cost, high linearity RF amplifier IC. The device is manufactured on an advanced Gallium Arsenide Heterojunction Bipolar Transistor (HBT) process, and has been designed for use as an easily cascadable 50Ω gain block. Applications include IF and RF amplification in wireless voice and data communication products operating in frequency bands up to 2500 MHz. The gain flatness over a very wide bandwidth makes the device suitable for many applications. The device is self-contained with 50Ω input and output impedances and requires only two external DC biasing elements to operate as specified.

0.008 0.050 NOTES: 1. Shaded lead is Pin 1. 2. All dimensions are excluding mold flash.
3. Lead ~ Lead coplanarity -0.005 with respect to datum "A" 0.009 0.034

Package Style: SOIC-8

Optimum Technology Matching® Applied

- ☐ Si BJT Si Bi-CMOS
- **▼** GaAs HBT ☐ SiGe HBT
- GaAs MESFET Si CMOS
- GalnP/HBT
- GaN HEMT
- SiGe Bi-CMOS



Functional Block Diagram

Features

- DC to well over 2500MHz Operation
- Internally Matched Input and Output
- 15dB Small Signal Gain
- 5dB Noise Figure
- +19dBm Output Power
- Single 3.5V to 6V Positive Power Supply

Ordering Information

RF2310 Wideband General Purpose Amplifier RF2310 PCBA Fully Assembled Evaluation Board

RF Micro Devices, Inc. Tel (336) 664 1233 7628 Thorndike Road Fax (336) 664 0454 Greensboro, NC 27409, USA http://www.rfmd.com

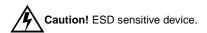
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RF2310

Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	-0.5 to +6.0	V_{DC}
Input RF Power	+10	dBm
Storage Temperature	-40 to +150	°C
Junction Temperature	175	°C
Thermal Resistance, Junction to Case	179	°C/W

Notes: case reference: pins 5-7, conditions: no signal in and both RF ports terminated in 50Ω ; average junction temperature measured at 85°C ambient: 143°C



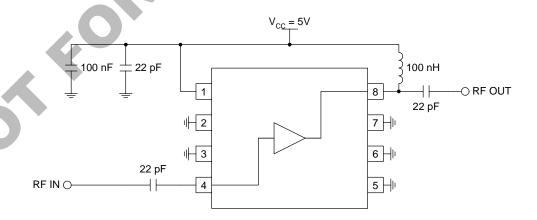
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Parameter	Specification		Unit	Condition		
Faranielei	Min.	Тур.	Max.	Offic	Condition	
Operating Range						
Overall Frequency Range	100		2500	MHz		
Supply Voltage	3.5		6.0	V		
Operating Current (I _{CC})		20	25	mA C	V _{CC} =3.6V, Temp=27°C	
	40	50	65	mA	V _{CC} =5V, Temp=27°C	
Operating Ambient Temperature	-40		+85	°C		
3.6V Performance						
Gain		16.2		dB	Freq=300MHz, V _{CC} =3.6V, Temp=27°C	
Gain		15.3		dB	Freq=900MHz, V _{CC} =3.6V, Temp=27°C	
Noise Figure		2.5		dB		
Output IP3		+22.0		dBm		
OP1dB		+10		dBm		
Gain		15		dB	Freq=1950MHz, V _{CC} =3.6V, Temp=27°C	
Noise Figure		2.7	•	dB		
Output IP3		+23.0		dBm		
OP1dB		+10		dBm		
Gain		16		dB	Freq=2450MHz, V _{CC} =3.6V, Temp=27°C	
Noise Figure		2.4		dB		
Output IP3		+21.0		dBm		
OP1dB		+10		dBm		
5 V Performance						
Gain		17		dB	Freq=300MHz, V _{CC} =5V, Temp=27°C	
Gain	14.0	16.5		dB	Freq=900MHz, V _{CC} =5V, Temp=27°C	
Noise Figure		3		dB		
Output IP3	+28.0	+31.0		dBm		
OP1dB		+17		dBm		
Gain		15.6		dB	Freq=1950MHz, V _{CC} =5V, Temp=27°C	
Noise Figure		3.5		dB		
Output IP3		+33.0		dBm		
OP1dB		+18		dBm	From 2450MHz V 5V Tomp 2720	
Gain		15		dB	Freq=2450MHz, V _{CC} =5V, Temp=27°C	
Noise Figure		2.8		dB dDm		
Output IP3		+26.0		dBm		
OP1dB		+17		dBm		

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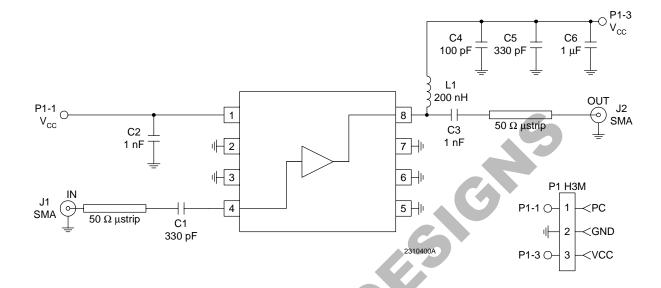
Pin	Function	Description	Interface Schematic
1	VCC	Power supply pin. An external bypass capacitor is recommended. The total supply current is shared between this pin and pin 8 (through the inductor).	vcc • • • • • • • • • • • • • • • • • •
2	GND	Ground connection. For best performance, keep traces physically short and connect immediately to ground plane. To achieve the performance as specified, and to minimize instability, it is recommended to have a local ground plane under the device, as shown in the evaluation board layout.	
3	GND	Same as pin 2.	
4	RF IN	RF input pin. This pin is NOT internally DC-blocked. A DC-blocking capacitor, suitable for the frequency of operation, should be used in most applications. DC-coupling of the input is not allowed, because this will override the internal feedback loop and cause temperature instability.	Bias RF IN O
5	GND	Same as pin 2.	
6	GND	Same as pin 2.	
7	GND	Same as pin 2.	
8	RF OUT	RF output and bias pin. Biasing is accomplished with an external choke inductor to $V_{\rm CC}$ that provides high impedance at the operating frequency. Because DC is present on this pin, a DC-blocking capacitor, suitable for the frequency of operation, should be used in most applications. The supply side of the bias network should also be well bypassed.	RF OUT

Application Schematic



Evaluation Board Schematic

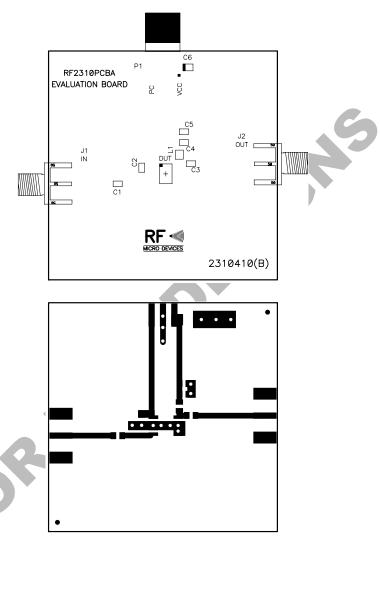
(Download Bill of Materials from www.rfmd.com.)

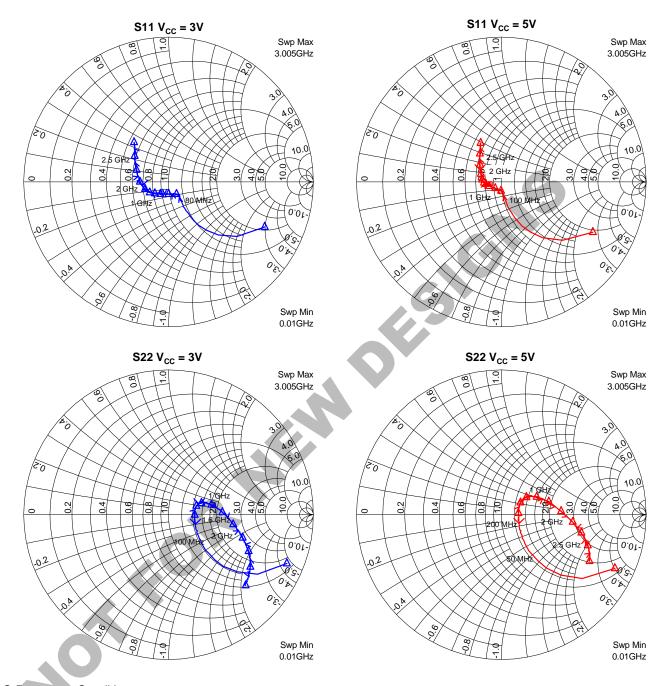


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Evaluation Board Layout Board Size 2.02" x 2.02"

Board Thickness 0.031", Board Material FR-4





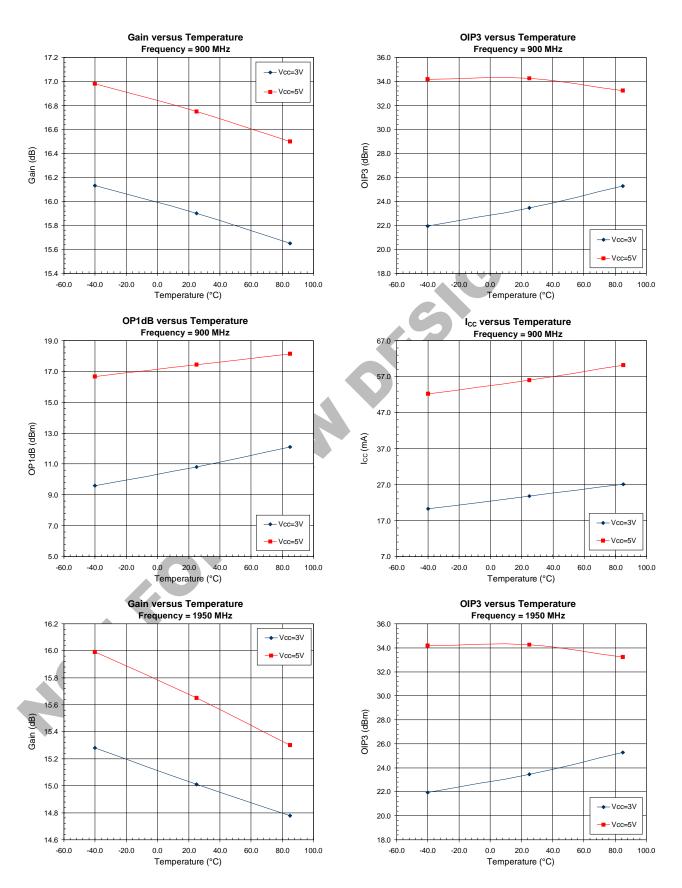
S-Parameter Conditions:

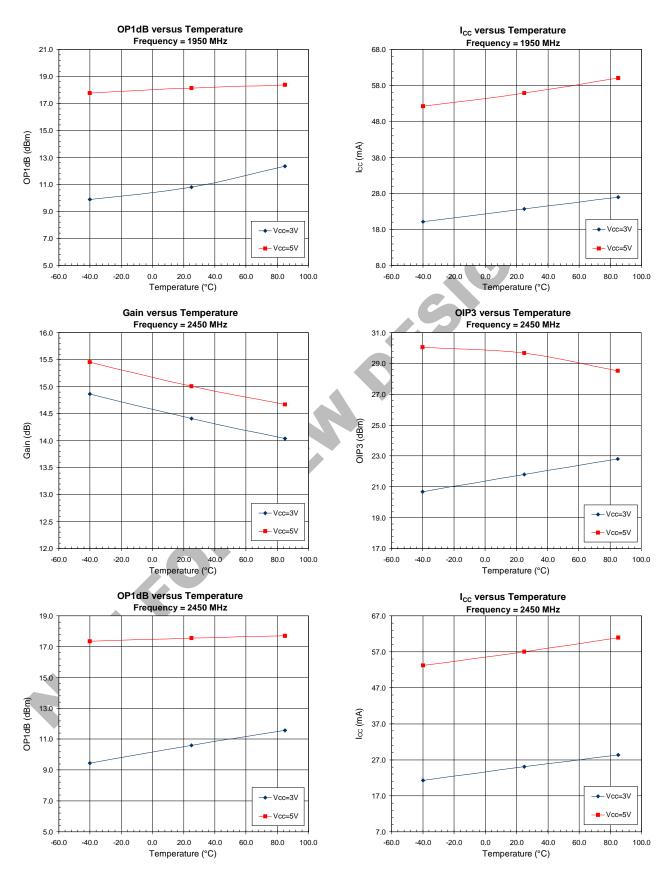
All plots are taken at ambient temperature=25°C.

NOTE:

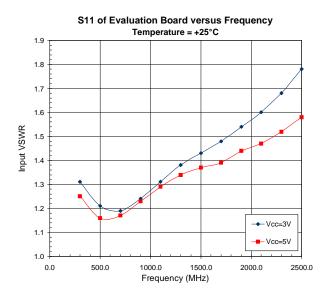
All S11 and S22 plots shown were taken from an RF2310 evaluation board with external input and output tuning components removed and the reference points at the RF IN and RF OUT pins.

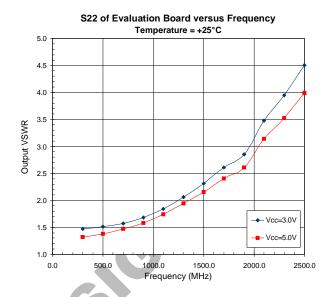
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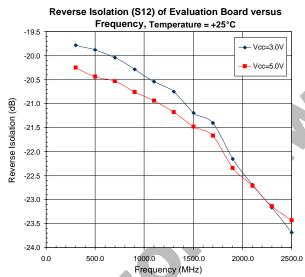




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